


## APPLICATION DATA SHEET

Electronic Version v14

Stylesheet Version v14.0

<b>Title of Invention</b>	IC PACKAGE HAVING GROUND IC CHIP AND METHOD OF MANUFACTURING SAME	
Application Type : regular, utility		
Attorney Docket Number : TSMC2003-1622		
Correspondence address:		
Customer Number:	44045	
Inventors Information:		
<u>Inventor 1:</u>		
<b>Applicant Authority Type:</b>	Inventor	
<b>Citizenship:</b>	TW	
<b>Given Name:</b>	PEI-HAW	
<b>Family Name:</b>	TSAO	
<b>Residence:</b>		
<b>City of Residence:</b>	Tai-chung	
<b>Country of Residence:</b>	TW	
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<b>City of Mailing Address:</b>	Tai-chung	
<b>State of Mailing Address:</b>		
<b>Postal Code of Mailing Address:</b>		
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<u>Inventor 2:</u>		
<b>Applicant Authority Type:</b>	Inventor	
<b>Citizenship:</b>	TW	
<b>Given Name:</b>	Chuen-Jye	
<b>Family Name:</b>	LIN	
<b>Residence:</b>		
<b>City of Residence:</b>	Tai-chung County	

**Country of Residence:** TW  
**Address-1 of Mailing Address:** No. 56-17, 320 Lane, 1st Section  
**Address-2 of Mailing Address:** Sha-Tian Road, Da-Du Township  
**City of Mailing Address:** Tai-chung County  
**State of Mailing Address:**  
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**Inventor 3:**

**Applicant Authority Type:** Inventor  
**Citizenship:** TW  
**Given Name:** Szu-Wei  
**Family Name:** LU  
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**Address-1 of Mailing Address:** No. 3, Lane 4, Anhe Street  
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**City of Mailing Address:** Hsinchu City  
**State of Mailing Address:**  
**Postal Code of Mailing Address:**  
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**Inventor 4:**

**Applicant Authority Type:** Inventor  
**Citizenship:** TW  
**Given Name:** Ching Chun  
**Family Name:** LU  
**Residence:**  
**City of Residence:** Taipei  
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**E-mail:**

**Inventor 5:**

**Applicant Authority Type:** Inventor

**Citizenship:** TW

**Given Name:** Chender

**Family Name:** HUANG

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**City of Residence:** Hsin-Chu

**Country of Residence:** TW

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**Inventor 6:**

**Applicant Authority Type:** Inventor

**Citizenship:** TW

**Given Name:** Mirng-Ji

**Family Name:** LII

**Residence:**

**City of Residence:** Lujhu Township

**Country of Residence:** TW

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